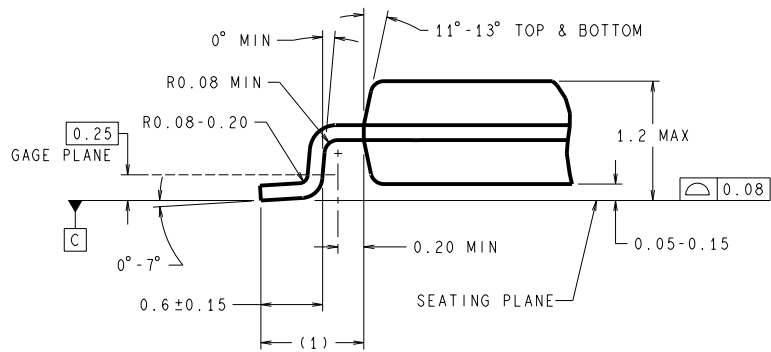


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12083	08/18/1998	MS/



DETAIL A
TYP, SCALE: 30X

- NOTES: UNLESS OTHERWISE SPECIFIED
- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
 - DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
 - NO JEDEC REGISTRATION AS OF AUG. 1998.

DIMENSIONS ARE IN MILLIMETERS

APPROVALS	DATE	National Semiconductor			
DRWN: MARTA SUCHY	08/18/1998	2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DFTG. CHK.		TQFP, 20 x 20 x 1.0mm, 128 LEAD, 0.5mm PITCH			
ENGR. CHK.					
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-VNH128A	A
		DO NOT SCALE DRAWING		SHEET 1 of 1	